

# **STRUCTURE OF PACKAGE FOR SEMICONDUCTOR IMAGE PICKUP DEVICE AND FABRICATION METHOD THEREOF**

## **ABSTRACT OF THE DISCLOSURE**

5           A package for semiconductor image pickup device is provided. The package is  
fabricated by using flip chip bumping. During deposition process of forming a metallic  
bonding layer and a metal layer for plating, a surface of a semiconductor image pickup device  
is maintained at the range between room temperature and 200°C in accordance with a first  
embodiment. A polymer layer for preventing stress from generating can absorb stress  
10 generated during the deposition process in accordance with a second embodiment. According  
to the present invention, a functional polymer layer on the surface of a semiconductor image  
pickup device can be prevented from being deteriorated in its properties and from transforming  
at its surface.